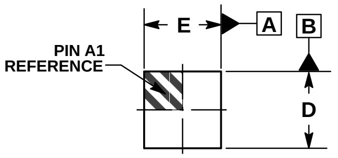
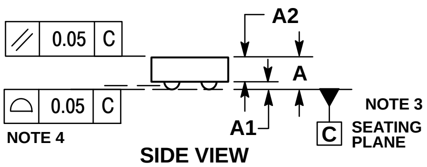
SCALE 4:1

WLCSP4, 0.84x0.84
CASE 567KV
ISSUE B

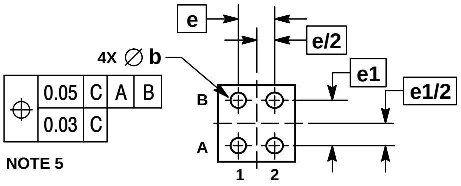
DATE 30 MAY 2017



TOP VIEW

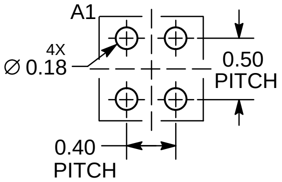


SIDE VIEW



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



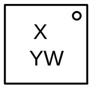
DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.

	MILLIMETERS		
DIM	**MIN**	**NOM**	**MAX**
A	−−−	−−−	0.35
A1	0.08	0.10	0.12
A2	0.23 REF		
b	0.16	0.18	0.20
D	0.81	0.84	0.87
E	0.81	0.84	0.87
e	0.40 BSC		
e1	0.50 BSC		

GENERIC MARKING DIAGRAM*



X = Specific Device Code
Y = Year
W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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STATUS:	**ON SEMICONDUCTOR STANDARD**	
NEW STANDARD:		
DESCRIPTION:	**WLCSP4, 0.84X0.84**	**PAGE 1 OF 2**

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY I. MARIANO.	30 OCT 2014
A	CHANGED DIMENSIONS D AND E FROM 0.85 NOMINAL TO MAX, REMOVED DIMENSIONAL TOLERANCE BOXES FROM TOP VIEW, CHANGED PACKAGE DESCRIPTION DIMENSIONS TO 0.84X0.84. REQ. BY A. SARWARI.	19 NOV 2014
B	SWAPPED DIMENSIONS FOR e AND e1 IN BOTTOM VIEW AND SOLDER FOOTPRINT. MODIFIED MIN & MAX VALUES FOR DIMENSIONS D & E. REQ. BY A. SARWARI.	30 MAY 2017

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